

JET SINGULATION

ABSTRACT OF THE DISCLOSURE

Techniques for singulating a substrate into a plurality of component parts is disclosed. The singulation techniques include generating a jet stream in order to cut through large components so as to produce smaller components. The techniques are particularly suitable for singulating surface mount devices such as chip scale packages, ball grid arrays (BGA), flip chips, lead less packages (QFN) and the like. The techniques are also suitable for singulating photonic devices.